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PATENT REEL: 018029 FRAME: 0841

## **ASSIGNMENT**

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned,

NAM, Ki-Won

Hereby sells, assigns, and transfers to:

Date: June 23 , 2006

**RECORDED: 06/28/2006** 

Hynix Semiconductor Inc.	
a corporation of Republic of Korea, having a principal place of business at:  San 136-1, Ami-ri, Bubal-eub, Ichon-shi, Kyoungki-do 467-860, Republic of Korea ("Assignee"), and its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent,	
[X] which has been executed by the undersigned concurrently herewith,	
which was filed and assigned Serial No,	
and is entitled:	
METHOD FOR FABRICATING SEMICONDUCTOR DEVICE	
and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;	
Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and	
Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.	

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**PATENT** REEL: 018029 FRAME: 0842

NAM Ki Win